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SMTA China to Host Comprehensive Conference at SMTA South China 2010

August 2010 — SMTA China will present the SMTA China South Conference during the upcoming NEPCON South China exhibition, scheduled to take place August 31-September 2, 2010 at the Shenzhen Convention and Exhibition Center in Shenzhen, China.

The technology conference will take place from 10:15 a.m.-3:15 p.m. on Tuesday, August 31 in two tracts: Emerging Technologies and Operation Excellence. All papers will be presented in Chinese.

The *Emerging Technologies* tract will be held in room 314, 3/F., at the Shenzhen Convention and Exhibition Center. The conference chairman will be Michael Y.F Wong, Vice President (Technology) of the SMTA HK Chapter and Director-Manufacturing Engineering-China Operation of Embedded Computing and Power of Emerson Network Power.

During this tract, several key presentations will be made:

10:15-10:45 a.m. "Organic Metal-based Nanofinish Technology for Advanced Surface Finishes" will be presented by Dr. Bernhard Wessling of Cookson Electronics-Enthone.

From 10:45-11:15 a.m., Indium Corp.'s Andy Wei will present "Understanding SIR."

11:15-11:45 a.m., Dr. Kenneth Lee of Atotech Deutschland GmbH will present "Gold Wire Bonding Performance and Reliability of ENEPIG Surface Finishes."

11:45 a.m.-12:15 p.m. "Micros Conformal Coating Intricate Electronic Devices" will be presented by PVA's Jon Urquhart

After a lunch break (12:15-1:45 p.m.), Andy Yuen of Cookson Electronics-ALPHA will present "Understanding the Head-In-Pillow Defects — Effect of the Flux Chemistry."

From 2:15-2:45 p.m., "The Effects of Nitrogen Atmospheres in Reflow and Wave Soldering Processes" will be presented by Air Products & Chemical Inc.'s Victor Wang.

The Emerging Technologies session will end with CALCE's Dr. Ricky Lee's presentation "Concerns with Interconnect Reliability Assessment of High Power Light Emitting Diodes (LEDs)" from 2:45-3:15 p.m.

Held simultaneously, the *Operation Excellence* tract will take place in room 316, 3/F. The conference chairman for this tract will be Maverick Luk, SMTA HK Chapter's President and Public Relations Manager of Electronic Technology Publishing Group.

Presentations include:

10:15-10:45 a.m. "INEMI Solder Paste Deposition Project Report — Optimizing Solder Paste Printing for Large and Small Components" by Huawei Technologies Co.Ltd.'s Laye Feng.

From 10:45-11:15 a.m., Shenzhen Kaifa Technology Co., Ltd.'s Xu Zheng will present "Effect



of PCB Surface Finishes on Microstructure and Shear-Strength of Lead-Free Solder Joint.”
11:15-11:45 p.m. Tony Ge of ZESTRON Asia North will present “Limitations of DI-Water Cleaning Processes.”

11:45 a.m.-12:15 p.m. “Integrating Cleaning Equipment and Cleaning Agent for Maximum Performance” will be presented by Kyzen’s Chris Harvey.

Lunch will take place from 12:15-1:45 p.m.

Following lunch, K.S. Seet of KIC will present “Thermal Process Optimization provides reduced energy consumption” from 1:45-2:15 p.m.

2:15-2:45 p.m. “Lead-Free PTH Rework Process Challenges and Solutions for a Server Complexity PCBA” will be presented by PK Pu of IBM CPC.

Finally, from 2:45-3:15 p.m., Dr. Ningcheng Lee of Indium Corp. will finish the Operation Excellence tract with the presentation “Testing and Prevention of Head-In-Pillow.”

Additionally, from Tuesday, August 31-Thursday, September 2, free vendor conferences will be held in Booth 3A15, Hall 3 of the convention center from 9:30 a.m.-4 p.m.

For more information about the SMTA China or to register for the SMTA China South Technical Conference, contact Ms. Peggy Chen at +86-21-5609-3010; fax: +86-21-5609-3020; E-mail: peggy@smta.org.

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